^{내외경제} 「Korea)

EV Group announces "NanoCleave technology" layer release technology - January 30, 2024

EVG introduced NanoCleave[™], a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. NanoCleave enables silicon wafer carriers in advanced packaging processes such as FoWLP using mold and reconstituted wafers as well as interposers for 3D SIC. "NanoCleave will help enable our customers to realize their advanced device and packaging roadmaps through a highly versatile and universal layer release technology that works with standard silicon wafers and wafer processes − enabling seamless integration in the fab and saving our customers both time and money." stated Paul Lindner, executive technology director at EV Group.



https://www.datanews.co.kr/news/article.html?no=131253